

Material Composition Specification

TLM2D3D6 Case



Top View Bottom View

Device average mass 144 µg

Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(µg)			(%wt)	(µg)	(ppm)
active device	doped Si	6.92%	10	Si	7440-21-3	6.92%	10	69,247
bond wire	gold	0.28%	0.4	Au	7440-57-5	0.28%	0.4	2,770
leadframe	Cu alloy	27.44%	39.63	Cu	7440-50-8	27.23%	39.33	272,350
				Sn	7440-31-5	0.07%	0.1	692
				Zn	7440-66-6	0.07%	0.1	692
				Cr	7440-47-3	0.07%	0.1	692
die attach	silver epoxy	2.77%	4	Ag	7440-22-4	1.94%	2.8	19,389
				epoxy resin	Proprietary	0.83%	1.2	8,310
encapsulation*	EMC GREEN	62.32%	90	silica (fused)	60676-86-0	52.97%	76.5	529,742
				epoxy resin	29690-82-2	4.67%	6.75	46,742
				phenol resin	9003-35-4	1.56%	2.25	15,581
				carbon black	1333-86-4	0.19%	0.27	1,870
				metal hydroxide	1309-42-8	2.93%	4.23	29,292
plating	Ni/Pd/Au	0.26%	0.38	Ni	7440-02-0	0.25%	0.36	2,493
				Pd	7440-05-3	0.01%	0.01	69
				Au	7440-57-5	0.01%	0.01	69

*EMC GREEN molding compound is Halogen-Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R1 (3-June 2011)